

LNPTM STAT-KONTM COMPOUND DE0026E

DC-FR

DESCRIPTION

LNP STAT-KON DE0026E compound is based on Polycarbonate (PC) resin containing 10% carbon fiber. Added features of this grade include Non-Chlorinated, Non-Brominated Flame Retardant, Electrically Conductive and Easy Molding.

GENERAL INFORMATION	
Features	Flame Retardant, Electrically Conductive, Good Processability, Non CI/Br flame retardant, Carbon fiber filled, High stiffness/Strength
Fillers	Carbon Fiber
Polymer Types	Polycarbonate (PC)
Processing Techniques	Injection Molding

INDUSTRY	SUB INDUSTRY	
Electrical and Electronics	Electronic Components	
Industrial	Material Handling	

TYPICAL PROPERTY VALUES

Revision 20240422

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL (1)			
Tensile Stress, yield, 5 mm/min	117	MPa	ISO 527
Tensile Strain, yield, 5 mm/min	2.7	%	ISO 527
Tensile Modulus, 1 mm/min	8000	MPa	ISO 527
Flexural Stress, yield, 2 mm/min	182	MPa	ISO 178
Flexural Modulus, 2 mm/min	7000	MPa	ISO 178
IMPACT (1)			
Izod Impact, notched 80*10*4 +23°C	10	kJ/m²	ISO 180/1A
THERMAL (1)			
CTE, 23°C to 60°C, flow	1.8E-05	1/°C	ISO 11359-2
CTE, 23°C to 60°C, xflow	7.4E-05	1/°C	ISO 11359-2
HDT/Bf, 0.45 MPa Flatw 80*10*4 sp=64mm	143	°C	ISO 75/Bf
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	140	°C	ISO 75/Af
Relative Temp Index, Elec (2)	80	°C	UL 746B
Relative Temp Index, Mech w/impact (2)	80	°C	UL 746B
Relative Temp Index, Mech w/o impact (2)	80	°C	UL 746B
PHYSICAL (1)			
Density	1.23	g/cm³	ISO 1183
Mold Shrinkage, flow ⁽³⁾	0.1 – 0.3	%	SABIC method
Mold Shrinkage, xflow (3)	0.2 – 0.4	%	SABIC method
ELECTRICAL (1)			
Surface Resistivity (4)	1.E+02 – 1.E+06	Ω	ASTM D257



PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
FLAME CHARACTERISTICS (2)			
UL Yellow Card Link	E45329-101357490	-	-
UL Recognized, 94V-0 Flame Class Rating	2	mm	UL 94
INJECTION MOLDING (5)			
Drying Temperature	120	°C	
Drying Time	4	Hrs	
Maximum Moisture Content	0.02	%	
Melt Temperature	305 – 325	°C	
Front - Zone 3 Temperature	320 – 330	°C	
Middle - Zone 2 Temperature	310 – 320	°C	
Rear - Zone 1 Temperature	295 – 305	°C	
Mold Temperature	80 – 110	°C	
Back Pressure	0.2 – 0.3	MPa	
Screw Speed	30 – 60	rpm	

- (1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.
- (2) UL Ratings shown on the technical datasheet might not cover the full range of thicknesses and colors. For details, please see the UL Yellow Card.
- (3) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.
- (4) Measurement meets requirements as specified in ASTM D4496.
- (5) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

MORE INFORMATION

For curve data and CAE cards, please visit and register at https://materialfinder.sabic-specialties.com

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